

PTC thermistors for overcurrent protection in telecom applications

Leadless round disks

Sei	ies	/Ty	pe:

Date: November 2009

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Leadless round disks

Applications

- Overcurrent protection for telecom applications
- Suitable for MDF applications e.g. connectors etc.

Features

- Designed for combined usage of PTC and primary protection (e.g. gas arrester)
- Suitable for continuous connection to mains voltages of 110/230 V AC in tripped (high-ohmic) condition
- Matching available with narrow resistance tolerance
- Tight resistance matching maintained after switching
- Negligible resistance drift after soldering or switching
- RoHS-compatible

Options

Alternative tolerances and resistances on request

Delivery mode

Packed in blister trays

General electrical data

Max. operating voltage		V_{max}	245	V AC
Operating temperature range	(V = 0)	T _{op}	-20/+125	°C
Operating temperature range	(V = 230 V)	T _{op}	0/+70	°C

Electrical specifications and ordering codes¹⁾

Туре	R_R	ΔR_R	R _{25,match}	I _R	I _R	Is	I _{Smax}	t _s (typ.)	Ordering code
			(per packing unit)	@	@	@	@	@ I _{Smax,}	_
			$ \mathbf{R}_1 - \mathbf{R}_2 _{max}$	25°C	70°C	25°C	230 V AC	230 V AC	
	Ω	%	Ω	mA	mA	mA	Α	s	
Round	disks,	conta	cts for clamp conne	ection					
A93	4.75	±15	0.9	160	70	370	1.0	4	B59093A0080B110
A95	9.3	±10	0.4	110	50	250	0.5	12	B59095A0080B110
Round disks, contacts for solder connection									
A1037	10	±15	No	140	95	300	1.0	2.0	B59037A1120B010
A1037	10	±15	1.0	140	95	300	1.0	2.0	B59037A1120B110
A1042	10	±15	1.0	150	100	300	1.0	4.0	B59042A1120B110
A1041	25	±15	1.0	100	65	200	2.8	0.2	B59041A1120B110
A1044	35	±15	1.0	90	55	180	2.8	1.15	B59044A1120B110

¹⁾ Variation of current and switching time with heat dissipation of mounting assembly must be taken into account.

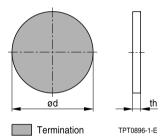


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Reliability data

Test	Standard	Test conditions	$ \Delta R_{25}/R_{25} $
Electrical endurance, cycling	IEC 60738-1	Room temperature, I _{Smax} ; V _{max} Number of cycles: 10	< 20%
Electrical endurance, constant	IEC 60738-1	Storage at V _{max} /T _{op} Test duration: 1000 h	< 25%
Damp heat	IEC 60738-1	Temperature of air: 40 °C Relative humidity of air: 93% Duration: 56 days Test according to IEC 60068-2-78	< 10%

Dimensional drawing



Dimensions in mm

Туре	$\emptyset d_{max}$	th _{max}	Contacts		
Round disks					
A1037	6.6	1.7	for solder connection		
A1041	8.1	2.1	for solder connection		
A1042	8.1	2.1	for solder connection		
A1044	8.1	2.1	for solder connection		
A93	7.9	2.1	for clamp connection		
A95	7.8	2.6	for clamp connection		



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Cautions and warnings

General

- EPCOS thermistors are designed for specific applications and should not be used for purposes not identified in our specifications, application notes and data books unless otherwise agreed with EPCOS during the design-in-phase.
- Ensure suitability of thermistor through reliability testing during the design-in phase. The thermistors should be evaluated taking into consideration worst-case conditions.

Storage

- Store thermistors only in original packaging. Do not open the package before storage.
- Storage conditions in original packaging: storage temperature −25 °C ... +45 °C, relative humidity ≤75% annual mean, maximum 95%, dew precipitation is inadmissible.
- Avoid contamination of thermistors surface during storage, handling and processing.
- Avoid storage of thermistor in harmful environment with effect on function on long-term operation (examples given under operation precautions).
- Use thermistor within the following period after delivery:
 - Through-hole devices (housed and leaded PTCs): 24 months
 - Motor protection sensors, glass-encapsulated sensors and probe assemblies: 24 months
 - Telecom pair and quattro protectors (TPP, TQP): 24 months
 - Leadless PTC thermistors for pressure contacting: 12 months
 - Leadless PTC thermistors for soldering: 6 months
 - SMDs in EIA sizes 3225 and 4032, and for PTCs with metal tags: 24 months
 - SMDs in EIA sizes 0402, 0603, 0805 and 1210: 12 months

Handling

- PTCs must not be dropped. Chip-offs must not be caused during handling of PTCs.
- Components must not be touched with bare hands. Gloves are recommended.
- Avoid contamination of thermistor surface during handling.

Soldering (where applicable)

- Use rosin-type flux or non-activated flux.
- Insufficient preheating may cause ceramic cracks.
- Rapid cooling by dipping in solvent is not recommended.
- Complete removal of flux is recommended.
- Standard PTC heaters are not suitable for soldering.



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Mounting

- Electrode must not be scratched before/during/after the mounting process.
- Contacts and housing used for assembly with thermistor have to be clean before mounting. Especially grease or oil must be removed.
- When PTC thermistors are encapsulated with sealing material, the precautions given in chapter "Mounting instructions", "Sealing and potting" must be observed.
- When the thermistor is mounted, there must not be any foreign body between the electrode of the thermistor and the clamping contact.
- The minimum force of the clamping contacts pressing against the PTC must be 10 N.
- During operation, the thermistor's surface temperature can be very high. Ensure that adjacent components are placed at a sufficient distance from the thermistor to allow for proper cooling at the thermistors.
- Ensure that adjacent materials are designed for operation at temperatures comparable to the surface temperature of thermistor. Be sure that surrounding parts and materials can withstand this temperature.
- Avoid contamination of thermistor surface during processing.

Operation

- Use thermistors only within the specified temperature operating range.
- Use thermistors only within the specified voltage and current ranges.
- Environmental conditions must not harm the thermistors. Use thermistors only in normal atmospheric conditions. Avoid use in deoxidizing gases (chlorine gas, hydrogen sulfide gas, ammonia gas, sulfuric acid gas etc), corrosive agents, humid or salty conditions. Contact with any liquids and solvents should be prevented.
- Be sure to provide an appropriate fail-safe function to prevent secondary product damage caused by abnormal function (e.g. use VDR for limitation of overvoltage condition).



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Symbols and terms

A Area

 $\begin{array}{ll} C_{th} & & \text{Heat capacity} \\ f & & \text{Frequency} \\ I & & \text{Current} \end{array}$

 I_{max}
 Maximum current

 I_R
 Rated current

 I_{PTC}
 PTC current

 I.
 Residual currrent

 $\begin{array}{ll} I_{\text{r,oil}} & \text{Residual currrent in oil (for level sensors)} \\ I_{\text{r,air}} & \text{Residual currrent in air (for level sensors)} \end{array}$

I_{RMS} Root-mean-square value of current

I_s Switching current

I_{Smax} Maximum switching current LCT Lower category temperature

N Number (integer)

N_c Operating cycles at V_{max}, charging of capacitor

N_f Switching cycles at V_{max}, failure mode

P Power

P₂₅ Maximum power at 25 °C

 P_{el} Electrical power P_{diss} Dissipation power R_{min} Minimum resistance R_{R} Rated resistance ΔR_{R} Tolerance of R_R Parallel resistance R_P R_{PTC} PTC resistance Reference resistance R_{ref} Series resistance R_s

R₂₅ Resistance at 25 °C
R_{25 match} Resistance matching per reel/ packing unit at 25 °C

 ΔR_{25} Tolerance of R_{25}

T Temperature

t Time

T_A Ambient temperaturet_a Thermal threshold time

T_C Ferroelectric Curie temperature



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t_E Settling time (for level sensors)

 $\begin{array}{lll} T_{\text{R}} & & \text{Rated temperature} \\ T_{\text{sense}} & & \text{Sensing temperature} \\ T_{\text{op}} & & \text{Operating temperature} \\ T_{\text{PTC}} & & \text{PTC temperature} \\ t_{\text{R}} & & \text{Response time} \end{array}$

T_{ref} Reference temperature

T_{Rmin} Temperature at minimum resistance

t_s Switching time

T_{surf} Surface temperature

UCT Upper category temperature

V or V_{el} Voltage (with subscript only for distinction from volume)

V_{RMS} Root-mean-square value of voltage

 V_{BD} Breakdown voltage V_{ins} Insulation test voltage $V_{link,max}$ Maximum link voltage V_{max} Maximum operating voltage

V_{max dvn} Maximum dynamic (short-time) operating voltage

V_{meas} Measuring voltage

V_{meas,max} Maximum measuring voltage

V_B Rated voltage

V_{PTC} Voltage drop across a PTC thermistor

α Temperature coefficient Δ Tolerance, change $δ_{th}$ Dissipation factor

τ_{th} Thermal cooling time constant

λ Failure rate

e Lead spacing (in mm)

Abbreviations / Notes

SMD Surface-mount devices

* To be replaced by a number in ordering codes, type designations etc.

+ To be replaced by a letter

All dimensions are given in mm.

The commas used in numerical values denote decimal points.



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